


IN THE CLAIMS

Please enter the following claims, including the new claims 68-75:

 54. (Unchanged) A polish pad comprising:

a center area;
a first set of grooves disposed in said center area, said first set of grooves having a first depth;
an edge area disposed adjacent to said center area; and
a second set of grooves disposed in said edge area, said second set of grooves having a second depth.

55. (Unchanged) The polish pad of claim 54 wherein said first depth is smaller than said second depth.

56. (Unchanged) The polish pad of claim 54 wherein said first depth is within the range of approximately 1-90 % of said pad thickness.

57. (Unchanged) The polish pad of claim 54 wherein said second depth is within the range of approximately 1-90 % of said pad thickness.

58. (Unchanged) The polish pad of claim 54 wherein said first set of grooves and said second set of grooves differ in shape.

59. (Unchanged) A polish pad comprising:

a center area;

a first set of grooves disposed in said center area, said first set of grooves having a first width;

an edge area disposed adjacent to said center area; and

a second set of grooves disposed in said edge area, said second set of grooves having a second width.

60. (Unchanged) The polish pad of claim 59 wherein said first width is smaller than said second width.

61. (Unchanged) The polish pad of claim 59 wherein said first width is within a range of approximately 1–100 mils.

62. (Unchanged) The polish pad of claim 59 wherein said second width is within the range of approximately 1–100 mils.

63. (Unchanged) The polish pad of claim 59 wherein said first set of grooves and said second set of grooves differ in shape.

Sub D3 64. (Unchanged) A polish pad comprising:

a center area;
a first set of grooves disposed in said center area, said first set of grooves having a first density;
an edge area disposed adjacent to said center area; and
a second set of grooves disposed in said edge area, said second set of grooves having a second density.

65. (Unchanged) The polish pad of claim 64 wherein said first density is smaller than said second density.

66. (Unchanged) The polish pad of claim 64 wherein said first density is within a range of approximately 2–50 grooves/inch.

67. (Unchanged) The polish pad of claim 64 wherein said second density is within a range of approximately 2–50 grooves/inch.

68. (New) An apparatus comprising:

a wafer, said wafer having a center area and an edge area; and
a polishing pad, said pad having a first set of grooves disposed over said center area and a second set of grooves disposed over said edge area, said second set of grooves being different from said first set of grooves.

69. (New) The apparatus of claim 68 wherein said first set of grooves and said second set of grooves differ in depth.

70. (New) The apparatus of claim 68 wherein said first set of grooves and said second set of grooves differ in width.

71. (New) The apparatus of claim 68 wherein said first set of grooves and said second set of grooves differ in density.

72. (New) The apparatus of claim 68 wherein said first set of grooves and said second set of grooves differ in shape.

73. (New) The apparatus of claim 68 further comprising a device for determining profile or topography of said wafer.

74. (New) the apparatus of claim 68 further comprising a device for determining high points and low points on surface of said wafer in said center area and said edge area.

75. (New) The apparatus of claim 68 further comprising slurry disposed in said first set of grooves and said second set of grooves.
